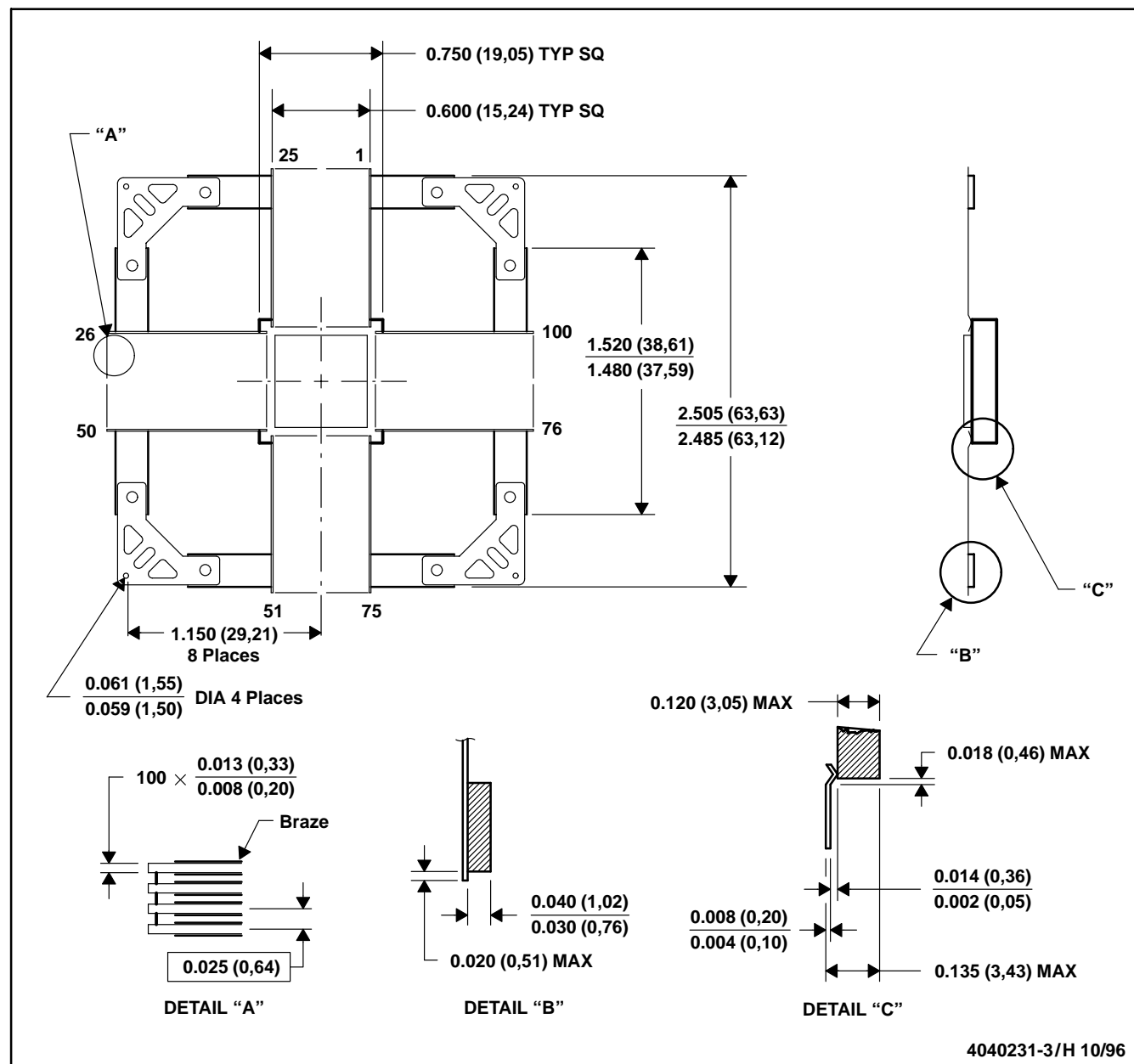


HFG (S-CQFP-F100)

CERAMIC QUAD FLATPACK WITH TIE BAR



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Ceramic quad flatpack with flat leads brazed to nonconductive tie-bar carrier
 D. This package can be hermetically sealed with a metal lid.
 E. The terminals are gold plated.
 F. Falls within JEDEC MO-113 AD

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